## ThinkStation P330 SFF Gen 2 (30D1 and 30D2) Platform Specifications

Components	Cracification	•						
Components Form footor	Specification							
Form factor	8.4L mini-tower							
Dimensions	Height: 343.5 mm (13.5 in). Width: 92.5 mm (3.6 in). Depth: 305.6 mm (12 in)							
Weight	Maximum configuration: 13.23 lb (6.0kg)							
	Supports one of the following processor:							
	Xeon E-2278G	8C/16T/3.4G	Hz/16MB/	80W/DE	R4-2666	(260W PS	U needed)	
	Xeon E-2276G	6C/12T/3.8G				1.		
	Xeon E-2274G	4C/8T/4.0GH						
	Xeon E-2246G	6C/12T/3.6G	Hz/12MB/	80W/DE	R4-2666			
Processor	Xeon E-2244G	4C/8T/3.8GH	lz/8MB/71	W/DDR4	4-2666			
	Xeon E-2236	6C/12T/3.4G	Hz/12MB/	80W/DE	R4-2666			
	Xeon E-2234	4C/8T/3.6GH	lz/8MB/71	W/DDR	4-2666			
	Xeon E-2226G	6C/6T/3.4GH						
	Xeon E-2224G	4C/4T/3.5GF						
	Xeon E-2224	4C/4T/3.4GH						
	Xeon E-2174G	4C/8T/3.8GF						
	Core i9-9900	8C/16T/3.1G						
	Core i7-9700	8C/8T/3.0GF						
	Core i7-8700	6C/12T/3.2G						
	Core i5-9600	6C/6T/3.1GH						
	Core i5-9500 Core i5-9400	6C/6T/3.0GF 6C/6T/2.9GF						
	Core i5-8500	6C/6T/3.0GF						
	Core i3-9300	4C/4T/3.7GF						
	Core i3-9300	4C/4T/3.6GF						
	Core i3-8300	4C/4T/3.7GF						
	Core i3-8100	4C/4T/3.6GH						
	Pentium Gold G5620	2C/4T/4.0GF						
Chipset	Intel C246 Chipset							
Memory Sockets	4 DIMM sockets with 2 channels							
Memory Types	8GB/16GB DDR4-2666 UDIMM ECC or 4GB/8GB/16GB DDR4-2666 UDIMM non-ECC							
Memory Capacity	64B with 4 x 16GB, both UDIMM ECC or UDIMM non-ECC							
Memory Protection								
Memory Protection	ECC on models with UDIMM ECC memeory  Three PCIs 3 0 slots as following:							
Expansion slots	Three PCIe 3.0 slots as following:							
	Slot 1 PCIe 3.0 x16, low profile, links to CPU							
	Slot 2 PCIe 3.0 x1, low profile, links to PCH							
	Slot 3 PCle 3.0 x16 (negotiable link width x4), low profile, links to PCH							
Processor graphics	Integrated Intel UHD Graphics P630 in -G suffix Xeon processors, or Intel UHD							
	Graphics 630 in Core i5 or i3 processors.							
	Works along with discrete graphics to support multi-display, enables three rear							
	display connectors (2 DP standard, 1 DP or HDMI optional)							
Discrete graphics card	Up to two PCle 3.0 x16 slots for discrete graphics adapter (Slot 1 and 3). Supports							
	the following graphics adapters:							
	Adapter Cor	es Memory	Power	Con	nectors	Max qty		
	Quadro P400 25				miniDP	2		
	Quadro P620 51				niniDP	2		
	Quadro P1000 64	0 4GB GDDF	R5 47W	4x r	niniDP	2		
Storage Controller	Storage Controller	Τν	pe Inte	face	Disk	Туре	RAID	
	Onboard Intel RST SATA RAID Std SATA 6Gb/s HDD or SSD 0/1							
	Onboard Intel RST PCIe RAID Std PCIe NVMe M.2 PCIe SSD 0/1							
	Notes: M.2 SSD support is limited, please see Storage bay section for more information							
Storage Support							·· Oh.	
		erface RPM		Offering	r <sub>R</sub>	ivla	x Qty 1	
		A 6Gb/s 7.2K		3/2TB/47			2	
	2.5" SATA HDD   SATA 6Gb/s   7.2K   500GB FIPS   2							
	Optane Memory PCIe NVMe 32GB 1, used with HDD/SSD							
		e NVMe	256GF	3/512GB	3/1TB	i, asea Wi	3	

	Components	Specification			
		Up to 3 bays with two disk bays and one slim optical bay:			
		Bay 1 Primary 3.5" SATA bay			
	Storage bay	Bay 2 2.5" SATA bay (Optional)			
		Bay 3 9mm Slim ODD bay			
		M.2 3x M.2 SSD (1 onboard. 2 via PCle to M.2 adapter) Notes: Support 1x M.2 SSD at present, 3x M.2 SSD support is pending availability			
	M.2 slot for Wi-Fi and Bluetooth	One dedicated onboard M.2 slot for optional Intel Wireless-AC 9560, 2x2, 2.4GHz/5GHz (160MHz channels), 802.11ac, Bluetooth 5, up to 1.73Gbps			
	Media reader	Optional SD card reader on most models			
	Network interfaces	One onboard GbE port via integrated gigabit ethernet Intel i219LM, supports Wake-on-LAN. Optional PCIe ethernet adapters are available			
	Security features	Power-on and admin password. Trusted Platform Module, TCG 2.0 compliant. Optional chassis intrusion switch, cable lock, Kensington lock, and pad lock			
	Intel vPro	Supports Intel vPro on Xeon models. vPro also requires Wireless-AC 9560 if Wi-Fi is needed			
	Intel AMT	Intel Active Management Technology 12 on Xeon models, Intel Standard Manageability on other models			
	Base warranty	US models comes with 3-year limited onsite service with 9x5/NBD.  1 or 3-year limited onsite service with 9x5/NBD in EMEA or other GEOs			
	HD Audio	Intel HD Audio interface with Realtek ALC233 Codec			
	Front ports	2x USB 3.1 Gen 1 Type A. 2x USB 3.1 Gen 2 Type A. 1x USB 3.1 Gen 1 Type-C. 1x Mic-in. 1x Combo jack			
	Rear ports	2x USB 3.1 Gen 1 Type A. 2x USB 2.0 Type-A. 1x RJ-45. 1x COM. 2x DP. 1x Audio line-out Notes: DP needs Core, Pentium, or -G suffix Xeon processor			
	Optional rear ports	Supports the following via cable: 1x COM. 1x Parallel. 2x PS/2. 1x DP or 1x HDMI. 2x USB 2.0 Supports the following via PCle adapter: 4x COM. 2x USB 3.1 Type-C. 2x USB 3.0. 1x Thunderbolt. Notes: DP or HDMI needs Core, Pentium, or -G suffix Xeon processor			
	Temperature	Operating: 50 °F to 95 °F (10 °C to 35 °C)  Non operating (no package): 14 °F to 140 °F (-10 °C to 60 °C)  Non operating (with package): -40 °F to 140 °F (-40 °C to 60 °C)			
٦	Altitude	titude Operating: -15.2 m (-50 ft) to 3048 m (10 000 ft).  Storage: -15.2 m (-50 ft) to 10, 668 m (35 000 ft)  Operating: 30%~90%, non-condensing Storage (with package): 20%~90%, non-condensing			
	Humidity				
_	Environmental				
	Power supply	Supports one 210W or 260W power supply. 210W is 100V - 240V, 85% PSU, Climate Savers Computing Bronze and 80			
;	. Sitor Suppry	260W is 100V - 240V, 92% PSU, Climate Savers Computing Platinum and 80 PLUS Platinum qualified			
	ISV certifications	Please visit www.thinkworkstations.com/isv-certifications/			
	Note:				

Note:
1. Depending on many factors, actual data transfer speed mentioned on this page may be lower than theoretical speed.
2. Any questions or advice on ThinkStation PSREF, please contact ThinkStation PSREF developer

